

pending the Examiner's further review when a response is filed. Arguments presented during the interview are reiterated below.

Claim 1 is directed to a surface acoustic wave component including a first layer located on a face of a piezoelectric substrate and having a hollowed out portion at least to a level of at least one active surface of the piezoelectric substrate. A printed circuit board covers the first layer and the hollowed out portion and conductive via holes go through the first layer and the printed circuit board so that the first layer completely surrounds each of the conductive via holes.

For example, as shown in Figure 3, the first layer 11 is disposed on the piezoelectric substrate 13 and a printed circuit 12 covers the first layer 11 and the hollow part of the first layer 11. The first layer 11 is disposed on the piezoelectric substrate 13 so that it completely surrounds each of the conductive via holes.

Takoshima discloses in Figure 3 an elastic surface wave element having a chip 11, a printed circuit 22, terminal sections 14 and 25 soldered together with soldering material 15, conductive via holes 30 disposed in the printed circuit 22, 23 and 24, and a sealing resin 27 disposed between the chip 12 and the printed circuit 22.¹ However, as shown in Figure 3 of Takoshima, the sealing resin 27 does not completely surround each of the conductive via holes 30.

Further, Onishi et al ('142), Tsuji et al and Onishi et al ('368) disclose conductive via holes going through a resin layer and a printed circuit board. However, completely surrounding each of the conductive via holes 30 with the resin layer in Takoshima is not possible because the conductive via holes 30 are completely embedded in the printed circuit board 22, 23, and 24. Therefore, even widening the sealing layer 27 as suggested in the

¹Takoshima, column 3, lines 28-36.

outstanding Office Action, will only surround the terminal sections 14 and 25, and not the conductive via holes 30, as in the present invention.

Thus, the combination of Takoshima and Onishi et al ('142), Tsuji et al or Onishi et al ('368) does not render obvious the invention of Claim 1. Accordingly, it is respectfully submitted independent Claim 1 and each of the claims depending therefrom are allowable.

Accordingly, in view of the foregoing, the present application is believed to be in condition for formal allowance. An early and favorable action is hereby respectfully requested.

Respectfully submitted,
OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.



Gregory J. Maier
Attorney of Record
Registration No. 25,599
David A. Bilodeau
Registration No. 42,325



22850

(703) 413-3000
Fax #: (703) 413-2220
GJM:DAB:RFF:smi
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IN THE CLAIMS

Please cancel Claims 7-14 without prejudice.

Please amend Claim 1 as follows:

1. (Twice Amended) A surface acoustic wave component comprising:
a piezoelectric substrate having a surface including at least one active surface;
at least two internal conductive contacts disposed on [the] a face of the piezoelectric substrate;
a first layer located on the face of the piezoelectric substrate and having a hollowed out [locally] portion at least to a level of the at least one active surface;
a printed circuit board covering the entire first layer and the hollowed out portion and having an opposing surface provided opposite the face of the piezoelectric substrate with the first layer disposed between said opposing surface and said face, said opposing surface having an area equal to an area of said face of said piezoelectric substrate, said printed circuit board further having external conductive contacts; and
conductive via holes going through the first layer and the printed circuit board and connecting the internal and external conductive contacts,

wherein the first layer completely surrounds each of the conductive via holes.

7.-14. (Cancelled)